

PRELIMINARY AMENDMENTS

1. A microwave package delimiting an interior volume,  
comprising at least:
  - 5 - a Faraday cage formed by a conducting surface  
surrounding the interior volume,
  - a connection point placed outside the Faraday  
cage, the connection point being intended to be  
linked electrically to an exterior circuit,
  - 10 - an input-output passing through the Faraday  
cage and linked electrically to the connection  
point,
  - a base forming a face of the package, the  
exterior surface of the base forming a mounting  
15 surface intended to be applied to the exterior  
circuit, the connection point being placed on  
the mounting surface, so that the connection  
point is placed between the Faraday cage and the  
exterior circuit when the package is mounted on  
20 the exterior circuit.
2. The package as claimed in claim 1, in which the  
connection point is linked to the input-output by  
a straight link, the link being perpendicular to  
25 the exterior circuit when the package is mounted  
on top.
3. The package as claimed in claim 1, in which the  
connection point is formed by a conducting signal  
30 ball.
4. The package as claimed in claim 1, whose base is  
formed at least in part by an insulating material  
covering at least one conducting layer, the input-  
35 output being formed by a metallized hole passing  
through the insulating material.

5. The package as claimed in claim 1, furthermore comprising a coaxial structure shielding the connection point.
- 5 6. The package as claimed in claims 5 and 3, in which the coaxial structure is formed by conducting earth balls, linked electrically to the Faraday cage, and placed around the signal ball.
- 10 7. The package as claimed in claim 6, in which the earth balls placed around the signal ball are at least three in number.
- 15 8. The package as claimed in claim 7, in which the earth balls are distributed around the signal ball over 360°.
- 20 9. The package as claimed in claim 1, in which a component is placed in the interior volume of the package, the component being carried by a radiator forming a face of the package, the radiator being opposite the face carrying the mounting surface.
- 25 10. A mounting comprising a package as claimed in claim 1 and a multilayer circuit, the package being mounted on the multilayer circuit, the multilayer circuit comprising at least one conducting earth plane, a metallized hole is made in the multilayer circuit opposite the connection point of the package, so as to convey the signal across the earth plane to a track of the circuit.
- 30 11. The mounting as claimed in claims 10 and 6, in which the earth balls of the package are linked to at least one conducting earth plane of the multilayer circuit.
- 35

12. The mounting as claimed in claim 10, comprising a second conducting earth plane, the two earth planes being on either side of the track.
- 5 13. The mounting as claimed in claim 10, in which the conducting earth planes of the circuit are linked together by metallized holes.